

高频高速铜箔基板



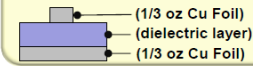
High Frequency and High Speed Flexible Copper Clad Laminate

产品特点 Product Feature

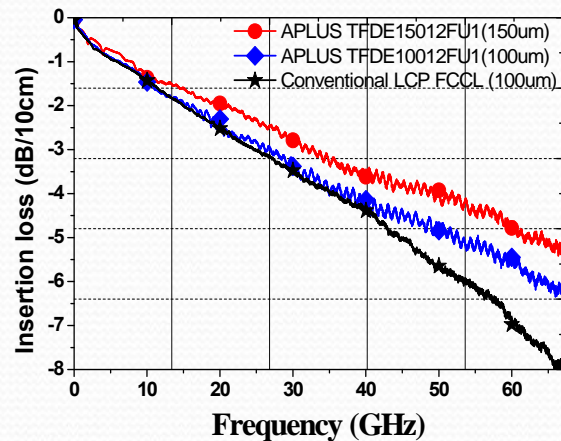
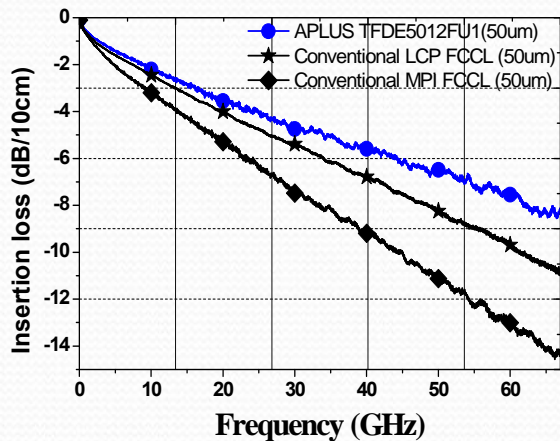
- 卓越的离子迁移特性 Outstanding performance of ion migration
- 低吸湿性 Low moisture absorption
- 低传输损耗特性 Low transmission loss

Microstrip line

Single-ended circuit



Line length : 100 mm.
Impedance : $50 \pm 2.5 \Omega$.
Test condition : 25°C, 50%RH.



产品特性 Characteristics

檢驗項目 Test Items	實驗條件 Condition of Testing	單位 Units	產品Product		測試方法 Test Method
			S/S FCCL TFS series	D/S FCCL TFD series	
绝缘层厚度 (Dielectric thickness)	A	μm	50/75/100	50/75/100/ 125/150	APLUS SPEC
剝離強度 (Peel strength)	A	kgf/cm	≥ 0.8	≥ 0.8	IPC-TM-650 2.4.9
尺寸安定性 (Dimensional stability)	MD	Method B/C	≤ ±0.08	≤ ±0.08	IPC-TM-650 2.2.4
	TD	Method B/C	≤ ±0.08	≤ ±0.08	
介電常數 Dk (Dielectric constant)	@15G Hz	-	~ 3.10	~ 3.10	IPC-TM-650 2.5.5.13
介電損失 Df (Dissipation factor)	@15G Hz	-	~ 0.0034	~ 0.0034	
吸水率 (Water absorption)	25°C, 24hr, water immersion	%	≤ 0.4	≤ 0.4	IPC-TM-650-2.6.2D
焊錫耐熱性 (Solder resistance)	10 seconds at 300°C	-	PASS	PASS	IPC-TM-650 2.4.13
耐燃性 (Flame class)	A	-	VTM-0	VTM-0	UL 94
儲存期限 (Shelf life)	5 ~ 35°C, 40-70%RH	month	12 months		APLUS SPEC

*所有数据为测试代表值 All data are representative value and not guarantee.